Microchip Filter specification TFS 1995 1/5

Measurement condition

Ambient temperature T_A : 23 °C Input power level: 0 dBm Terminating impedance:

Input: 50Ω Output: 50Ω

Characteristics

Remark:

The reference level for the relative attenuation a_{rel} is the maximum attenuation in the pass band. The maximum attenuation in the pass band is defined as the insertion loss a_e . The nominal frequency f_N is fixed at 1995 MHz without any tolerance or limit. The values of relative attenuation a_{rel} are guaranteed over the whole operating temperature range. The frequency shift of the filter within the operating temperature range is included in the production tolerance scheme.

Data				typ. value			tolerance / limit			
Insertion loss				a _e	2.2	dB	max.	3.0	dB	
Nominal frequency				f_N	-	-		1995.0	MHz	
Passband				РВ	-	-	f _N ±	15.0	MHz	
Pass band variation					0.6	dB	max.	1.5	dB	
Relative attenuation			a _{rel}	-	-					
30	MHz		1626	MHz		40	dB	min.	30	dB
1626	MHz		1656	MHz		51	dB	min.	40	dB
1656	MHz		1920	MHz		32	dB	min.	30	dB
2070	MHz		3000	MHz		35	dB	min.	30	dB
3000	MHz		4000	MHz		27	dB	min.	20	dB
VSWR within PB					1.5 : 1		max.	2:1		
Input power level					-		max.	10	dBm	
Operating temperature range				OTR	=		-40 °C +85 °C			
Storage temperature range					-		-55 °C +125 °C			
Temperature coefficient of frequency				TC _f *	-40	ppm/K				

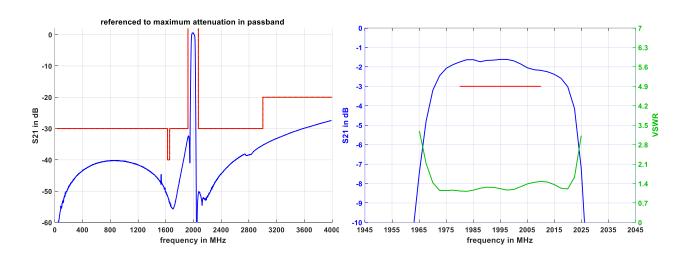
*	۱۸	f =	TC_f	T	_	T.	f.
	, 4	<i>ı</i> —	$I \cup_f$	· (1	_	I_{Δ}	IN

Generated:		

Checked / Approved:

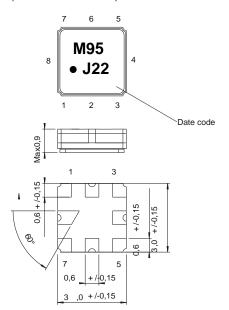
Microchip Filter specification TFS 1995 2/5

Filter characteristic



Construction and pin connection

(All dimensions in mm)



I	Ground
2	Input
3	Ground
1	Ground
5	Ground
3	Output
7	Ground
3	Ground

Date code: Year + week J 2017 K 2018 L 2019 ...

50 Ω Test circuit



Filter specification **TFS 1995** Microchip 3/5

Stability characteristics, reliability

After the following tests the filter shall meet the whole specification:

1. Shock: 500 g, 1 ms, half sine wave, 3 shocks each plane;

DIN IEC 60068 T2 - 27

2. Vibration: 10 Hz to 2000 Hz, 0.35 mm or 5 g respectively, 1 octave per min, 10 cycles per

plane, 3 planes; DIN IEC 60068 T2 - 6

3. Change of

temperature: -55 °C to 125 °C / 15 min. each / 100 cycles

DIN IEC 60068 part 2 - 14 Test N

4. Resistance to

solder heat (reflow): reflow possible: three times max.;

for temperature conditions refer to the attached "Air reflow temperature conditions" on page 4;

5. SAW devices are Electrostatic Discharge (ESD) sensitive devices.

This filter is RoHS compliant (2011/65/EU)

Packing

Tape & Reel: IEC 286 – 3, with exception of value for N and minimum bending radius;

tape type II, embossed carrier tape with top cover tape on the upper side;

max. pieces of filters per reel: 3000 min. 300 mm reel of empty components at start: reel of empty components at start including leader: min. 500 mm trailer: min. 300 mm

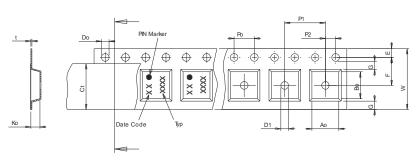
Pull Off Direction

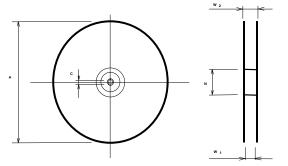
Tape (all dimensions in mm) 8.00 ±0.3

4.00 ±0.1 Ро Do +0.1/-0 E F 1.75 ±0.1 3.50 ±0.05 G(min) 0.75 P2 2.00 ±0.05 4.00 ±0.1 D1(min) 1.50 Αo 3.25 ±0.1 3.25 ±0.1 Ct 5.30 ±0.1 Ko 1.50 ±0.1 0.25 ±0.05

Reel (all dimensions in mm) :330 or 180 8.40 +1.5/-0 W/1 W2(max) 14.40

60.00 N(min) 13.0 ±0.2





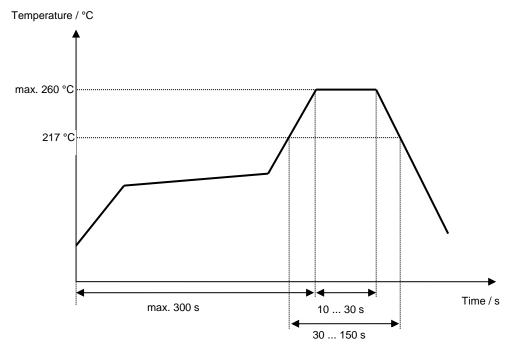
The minimum bending radius is 45 mm.

Microchip Filter specification TFS 1995 4/5

Air reflow temperature conditions

Conditions	Exposure
Average ramp-up rate (30 °C to 217 °C)	less than 3 °C / second
> 100 °C	between 300 and 600 seconds
> 150 °C	between 240 and 500 seconds
> 217 °C	between 30 and 150 seconds
Peak temperature	max. 260 °C
Time within 5 °C of actual peak temperature	between 10 and 30 seconds
Cool-down rate (Peak to 50 °C)	less than 6 °C / second
Time from 30 °C to Peak temperature	no greater than 300 seconds

Chip-mount air reflow profile



Microchip Filter specification TFS 1995 5/5

History

Version Reason of Changes Name Date

1.0 Generation of filter specification S.Springfeldt 01.06.2017